

NCV7380

LIN Transceiver

The NCV7380 is a physical layer device for a single wire data link capable of operating in applications where high data rate is not required and a lower data rate can achieve cost reductions in both the physical media components and in the microprocessor which uses the network. The NCV7380 is designed to work in systems developed for LIN 1.3 or LIN 2.0. The IC furthermore can be used in ISO9141 systems.

Because of the very low current consumption of the NCV7380 in recessive state, it's suitable for ECU applications with low standby current requirements, whereby no sleep/wakeup control from the microprocessor is necessary.

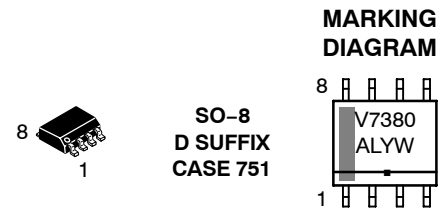
Features

- Operating Voltage $V_S = 7.0$ to 18 V
- Low Current Consumption of Typ. $24 \mu\text{A}$
- LIN-Bus Transceiver:
 - ◆ Slew Rate Control for Good EMC Behavior
 - ◆ Fully Integrated Receiver Filter
 - ◆ BUS Input Voltage -27 V to 40 V
 - ◆ Integrated Termination Resistor for LIN Slave Nodes ($30 \text{ k}\Omega$)
 - ◆ Baud Rate up to 20 kBaud
 - ◆ Will Work in Systems Designed for either LIN 1.3 or LIN 2.0
- Compatible to ISO9141 Functions
- High EMI Immunity
- Bus Terminals Protect Against Short-Circuits and Transients in the Automotive Environment
- Bus Pin High Impedance During Loss of Ground and Undervoltage Conditions
- Thermal Overload Protection
- High Signal Symmetry for use in RC-Based Slave Nodes up to 2% Clock Tolerance when Compared to the Master Node
- ± 1000 V ESD Protection, Charged Device Model
- NCV Prefix for Automotive and Other Applications Requiring Site and Change Control
- Pb-Free Packages are Available



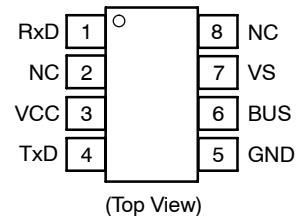
ON Semiconductor®

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V7380 = Specific Device Code
 A = Assembly Location
 L = Wafer Lot
 Y = Year
 W = Work Week
 ■ = Pb-Free Package

PIN CONNECTIONS



ORDERING INFORMATION

| Device | Package | Shipping† |
|-------------|-------------------|------------------|
| NCV7380D | SO-8 | 95 Units/Rail |
| NCV7380DG | SO-8 (Pb-Free) | 95 Units/Rail |
| NCV7380DR2 | SO-8 | 2500 Tape & Reel |
| NCV7380DR2G | SO-8 (Pb-Free) | 2500 Tape & Reel |

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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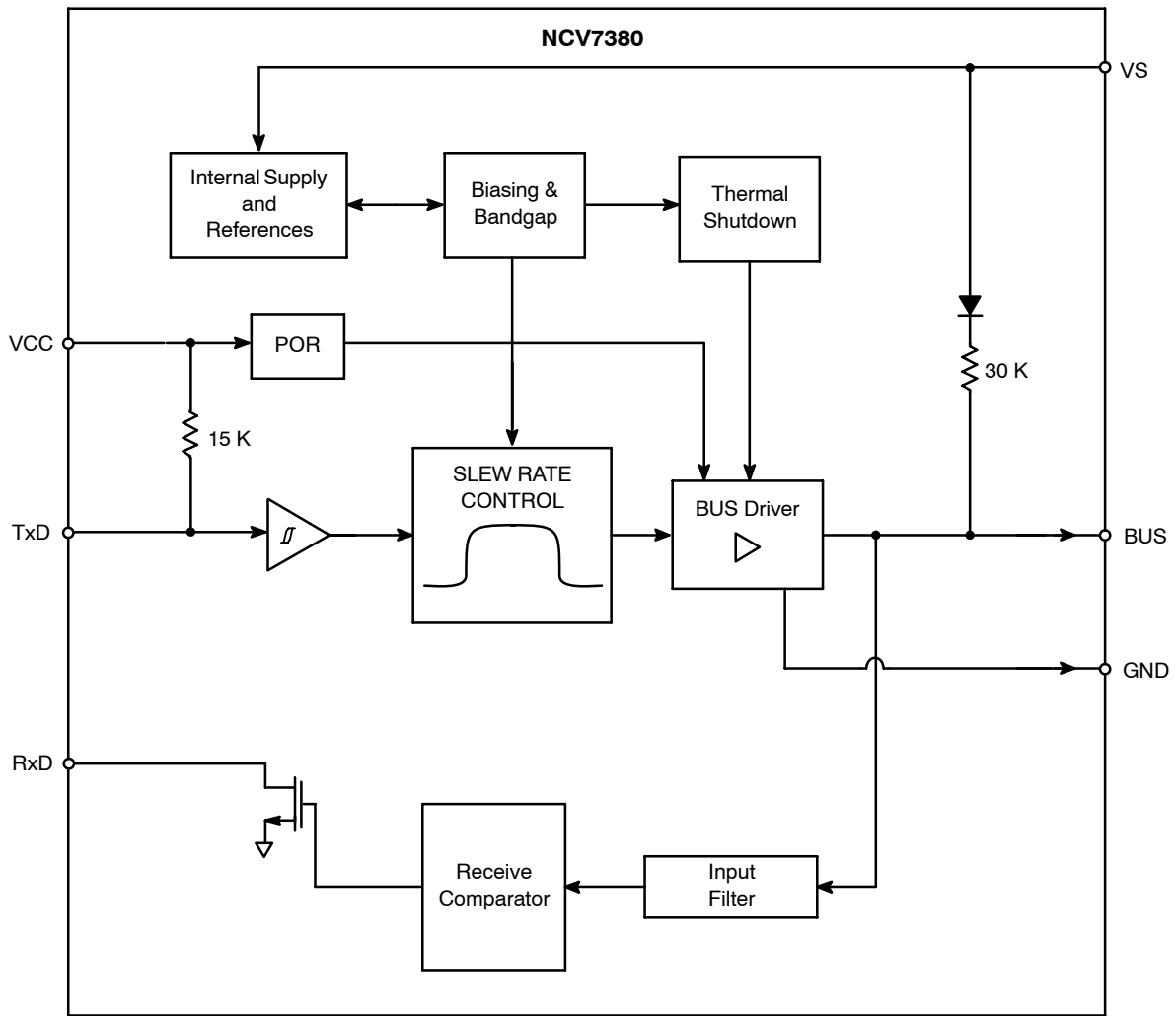


Figure 1. Block Diagram

PACKAGE PIN DESCRIPTION

| Pin | Symbol | Description |
|-----|--------|--|
| 1 | RxD | Receive data from BUS to microprocessor, LOW in dominant state. |
| 2 | NC | No connection. |
| 3 | VCC | 5.0 V supply input. |
| 4 | TxD | Transmit data from microprocessor to BUS, LOW in dominant state. |
| 5 | GND | Ground. |
| 6 | BUS | LIN bus pin, LOW in dominant state. |
| 7 | VS | Battery input voltage. |
| 8 | NC | No connection. |

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Electrical Specification

All voltages are referenced to ground (GND). Positive currents flow into the IC.

The maximum ratings given in the table below are limiting values that do not lead to a permanent damage of

the device but exceeding any of these limits may do so. Long term exposure to limiting values may effect the reliability of the device.

OPERATING CONDITIONS

| Characteristic | Symbol | Min | Max | Unit |
|---------------------------------|----------|-----|------|------|
| Battery Supply Voltage (Note 1) | V_S | 7.0 | 18 | V |
| Supply Voltage | V_{CC} | 4.5 | 5.5 | V |
| Operating Ambient Temperature | T_A | -40 | +125 | °C |

MAXIMUM RATINGS

| Rating | Symbol | Condition | Min | Max | Unit |
|--|---------------|---|------|------|------|
| Battery Supply Voltage | V_S | t < 1 min | -0.3 | 30 | V |
| | | Load Dump, t < 500 ms | | 40 | |
| Supply Voltage | V_{CC} | - | -0.3 | +7.0 | V |
| Transient Supply Voltage | $V_{S.tr1}$ | ISO 7637/1 Pulse 1 (Note 2) | -150 | - | V |
| Transient Supply Voltage | $V_{S.tr2}$ | ISO 7637/1 Pulses 2 (Note 2) | - | 100 | V |
| Transient Supply Voltage | $V_{S.tr3}$ | ISO 7637/1 Pulses 3A, 3B | -150 | 150 | V |
| BUS Voltage | V_{BUS} | t < 500 ms, $V_S = 18$ V | -27 | 40 | V |
| | | t < 500 ms, $V_S = 0$ V | -40 | | |
| Transient Bus Voltage | $V_{BUS.tr1}$ | ISO 7637/1 Pulse 1 (Note 3) | -150 | - | V |
| Transient Bus Voltage | $V_{BUS.tr2}$ | ISO 7637/1 Pulses 2 (Note 3) | - | 100 | V |
| Transient Bus Voltage | $V_{BUS.tr3}$ | ISO 7637/1 Pulses 3A, 3B (Note 3) | -150 | 150 | V |
| DC Voltage on Pins TxD, RxD | V_{DC} | - | -0.3 | 7.0 | V |
| ESD Capability, Charged Device Model | V_{ESDCDM} | (Note 4) | -1.0 | 1.0 | kV |
| ESD Capability of RxD, TxD, V_{CC} , BUS Pins ESD Capability of V_S Pin | V_{ESDHBM} | Human body model, equivalent to discharge 100 pF with 1.5 k Ω (Note 4) | -2.0 | 2.0 | kV |
| | | | -1.5 | 1.5 | kV |
| Maximum Latchup Free Current at Any Pin | I_{LATCH} | - | -500 | 500 | mA |
| Maximum Power Dissipation | P_{tot} | At $T_A = 125^\circ\text{C}$ | - | 197 | mW |
| Thermal Impedance | θ_{JA} | In Free Air | - | 152 | °C/W |
| Storage Temperature | T_{stg} | - | -55 | +150 | °C |
| Junction Temperature | T_J | - | -40 | +150 | °C |

LEAD TEMPERATURE SOLDERING REFLOW

| | | | | |
|--|-----------|---|----------|----|
| Lead Free, 60 sec -150 sec above 217, 40 sec Max at Peak | T_{SLD} | - | 265 Peak | °C |
| Leaded, 60 sec -150 sec above 183, 30 sec Max at Peak | T_{SLD} | - | 240 Peak | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- V_S is the IC supply voltage including voltage drop of reverse battery protection diode, $V_{DROD} = 0.4$ to 1.0 V, V_{BAT_ECU} voltage range is 7.0 to 18 V.
- ISO 7637 test pulses are applied to V_S via a reverse polarity diode and > 2.0 μF blocking capacitor.
- ISO 7637 test pulses are applied to BUS via a coupling capacitance of 1.0 nF.
- This device incorporates ESD protection and is tested by the following methods:
ESD HBM tested per AEC-Q100-002 (EIA/JESD22-A 114C)
ESD CDM tested per EIA/JESD22-C 101C, Field Induced Model.

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ELECTRICAL CHARACTERISTICS ($V_S = 7.0$ to 18 V, $V_{CC} = 4.5$ to 5.5 V and $T_A = -40$ to 125°C unless otherwise noted.)

| Characteristic | Symbol | Condition | Min | Typ | Max | Unit |
|-------------------------------|--------------------|--|------|-----|-----|------------------|
| GENERAL | | | | | | |
| V_{CC} Undervoltage Lockout | V_{CC_UV} | $V_S > 6.0$ V, TxD = L, EN = H | 2.75 | – | 4.3 | V |
| Supply Current, Dominant | I_{sd} | $V_S = 18$ V, $V_{CC} = 5.5$ V, TxD = L | – | 1.0 | 3.0 | mA |
| Supply Current, Dominant | I_{CCd} | $V_S = 18$ V, $V_{CC} = 5.5$ V, TxD = L | – | 0.8 | 1.5 | mA |
| Supply Current, Recessive | I_{sr} | $V_S = 18$ V, $V_{CC} = 5.5$ V, TxD = Open | – | 10 | 20 | μA |
| Supply Current, Recessive | I_{CCr} | $V_S = 18$ V, $V_{CC} = 5.5$ V, TxD = Open | – | 14 | 30 | μA |
| Supply Current, Recessive | $I_{Sr} + I_{CCr}$ | $V_S = 12$ V, $V_{CC} = 5.0$ V, TxD = Open, $T_A = 25^\circ$ | – | 24 | – | μA |
| Thermal Shutdown | T_{sd} (Note 5) | – | 155 | – | 180 | $^\circ\text{C}$ |
| Thermal Recovery | T_{hys} (Note 5) | – | 126 | 140 | 150 | $^\circ\text{C}$ |

BUS – Transmit

| | | | | | | |
|-------------------------------------|--|--|------|-----|------|---------------|
| Short Circuit Bus Current | I_{BUS_LIM} (Notes 6 and 7) | $V_{BUS} = V_S$, Driver On | – | 120 | 200 | mA |
| Pullup Current Bus | I_{BUS_PU} (Notes 6 and 7) | $V_{BUS} = 0$, $V_S = 12$ V, Driver Off | –600 | – | –200 | μA |
| Bus Reverse Current, Recessive | $I_{BUS_PAS_rec}$ (Notes 6 and 7) | $V_{BUS} > V_S$, 8.0 V $< V_{BUS} < 18$ V, 7.0 V $< V_S < 18$ V, Driver Off | – | – | 5.0 | μA |
| Bus Reverse Current Loss of Battery | I_{BUS} (Notes 6 and 7) | $V_S = 0$ V, 0 V $< V_{BUS} < 18$ V | – | – | 5.0 | μA |
| Bus Current During Loss of Ground | $I_{BUS_NO_GND}$ (Notes 6 and 7) | $V_S = 12$ V, $0 < V_{BUS} < 18$ V | –1.0 | – | 1.0 | mA |
| Transmitter Dominant Voltage | $V_{BUSdom_DRV_2}$ (Note 6) | $V_S = 7.0$ V, Load = 500Ω | – | – | 1.2 | V |
| Transmitter Dominant Voltage | $V_{BUSdom_DRV_3}$ (Note 6) | $V_S = 18$ V, Load = 500Ω | – | – | 2.0 | V |
| Bus Input Capacitance | C_{BUS} (Note 5) | Pulse Response via 10 k Ω , $V_{PULSE} = 12$ V, $V_S = \text{Open}$ | – | 25 | 35 | pF |

BUS – Receive

| | | | | | | |
|------------------------------------|-----------------------------------|--|---------------|--------------|---------------|---|
| Receiver Dominant Voltage | V_{BUSdom} (Notes 6 and 7) | – | $0.4 * V_S$ | – | – | V |
| Receiver Recessive Voltage | V_{BUSrec} (Notes 6 and 7) | – | – | – | $0.6 * V_S$ | V |
| Center Point of Receiver Threshold | V_{BUS_CNT} (Notes 6 and 7) | $V_{BUS_CNT} = (V_{BUSdom} + V_{BUSrec})/2$ | $0.487 * V_S$ | $0.5 * V_S$ | $0.512 * V_S$ | V |
| Receiver Hysteresis | V_{HYS} (Notes 6 and 7) | $V_{BUS_CNTt} = (V_{BUSrec} - V_{BUSdom})$ | – | $0.16 * V_S$ | – | V |

5. No production test, guaranteed by design and qualification.
6. In accordance to LIN physical layer specification 1.3.
7. In accordance to LIN physical layer specification 2.0.

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ELECTRICAL CHARACTERISTICS (continued) ($V_S = 7.0$ to 18 V, $V_{CC} = 4.5$ to 5.5 V and $T_A = -40$ to 125°C unless otherwise noted.)

| Characteristic | Symbol | Condition | Min | Typ | Max | Unit |
|--------------------------|---------------|-----------------|--------------------|-----|--------------------|------------|
| TXD | | | | | | |
| High Level Input Voltage | V_{ih} | Rising Edge | - | - | $0.7 \cdot V_{CC}$ | V |
| Low Level Input Voltage | V_{il} | Falling Edge | $0.3 \cdot V_{CC}$ | - | - | V |
| TxD Pullup Resistor | R_{IH_TXD} | $V_{TXD} = 0$ V | 10 | 15 | 25 | k Ω |

RXD

| | | | | | | |
|--------------------------|-----------------|------------------------------|-----|---|-----|---------------|
| Low Level Output Voltage | V_{ol_rxd} | $I_{RXD} = 2.0$ mA | - | - | 0.9 | V |
| Leakage Current | V_{leak_rxd} | $V_{RXD} = 5.5$ V, Recessive | -10 | - | 10 | μA |

AC CHARACTERISTICS

| | | | | | | |
|--|--------------------------------------|--|------------|--------|------------|--|
| Propagation Delay Transmitter (Notes 10 and 12) | t_{trans_pdf} t_{trans_pdr} | Bus Loads: 1.0 K Ω / 1.0 nF, 660 Ω / 6.8 nF, 500 Ω / 10 nF | - | - | 5.0 | μs |
| Propagation Delay Transmitter Symmetry (Notes 8 and 12) | t_{trans_sym} | Calculate $t_{trans_pdf} - t_{trans_pdr}$ | -2.0 | - | 2.0 | μs |
| Propagation Delay Receiver (Notes 8, 9, 10, 12 and 15) | t_{rec_pdf} t_{rec_pdr} | $C_{RXD} = 20$ pF | - | - | 6.0 | μs |
| Propagation Delay Receiver Symmetry (Notes 8 and 9) | t_{rec_sym} | Calculate $t_{trans_pdf} - t_{trans_pdr}$ | -2.0 | - | 2.0 | μs |
| Slew Rate Rising and Falling Edge, High Battery (Notes 8 and 13) | t_{SR_HB} | Bus Loads: $V_S = 18$ V, 1.0 K Ω / 1.0 nF, 660 Ω / 6.8 nF, 500 Ω / 10 nF | 1.0 | 2.0 | 3.0 | V/ μs |
| Slew Rate Rising and Falling Edge, Low Battery (Notes 8 and 13) | t_{SR_LB} | Bus Loads: $V_S = 7.0$ V, 1.0 K Ω / 1.0 nF, 660 Ω / 6.8 nF, 500 Ω / 10 nF | 0.5 | 2.0 | 3.0 | V/ μs |
| Slope Symmetry, High Battery (Notes 8 and 13) | t_{ssym_HB} | Bus Loads: $V_S = 18$ V, 1.0 K Ω / 1.0 nF, 660 Ω / 6.8 nF, 500 Ω / 10 nF, Calculate $t_{sdom} - t_{srec}$ | -5.0 | - | 5.0 | μs |
| Bus Duty Cycle (Notes 9 and 16) | D1 D2 | Calculate $t_{BUS_rec(min)}/100$ μs Calculate $t_{BUS_rec(max)}/100$ μs | 0.396 - | - - | - 0.581 | $\mu\text{s}/\mu\text{s}$ $\mu\text{s}/\mu\text{s}$ |
| Receiver Debounce Time (Notes 11, 14 and 15) | t_{rec_deb} | BUS Rising and Falling Edge | 1.5 | - | 4.0 | μs |

8. In accordance to LIN physical layer specification 1.3.

9. In accordance to LIN physical layer specification 2.0.

10. Propagation delays are not relevant for LIN protocol transmission, only symmetry.

11. No production test, guaranteed by design and qualification.

12. See Figure 2 – Input/Output Timing.

13. See Figure 7 – Slope Time Calculation.

14. See Figure 3 – Receiver Debouncing.

15. This parameter is tested by applying a square wave to the bus. The minimum slew rate for the bus rising and falling edges is 50 V/ μs .

16. See Figure 8 – Duty Cycle Measurement and Calculation.

TIMING DIAGRAMS

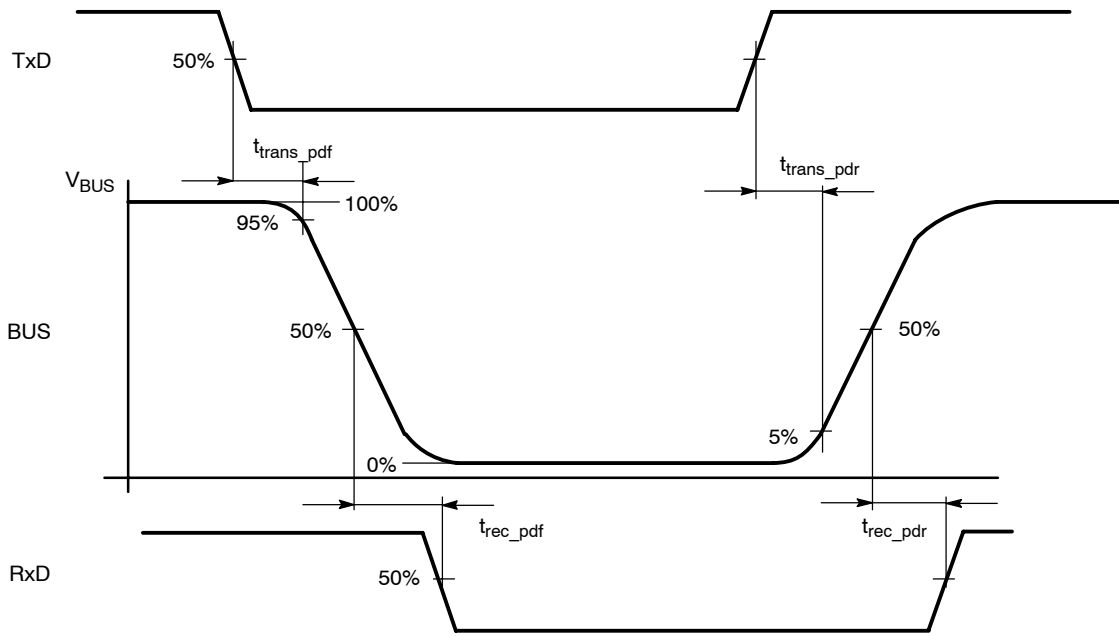


Figure 2. Input/Output Timing

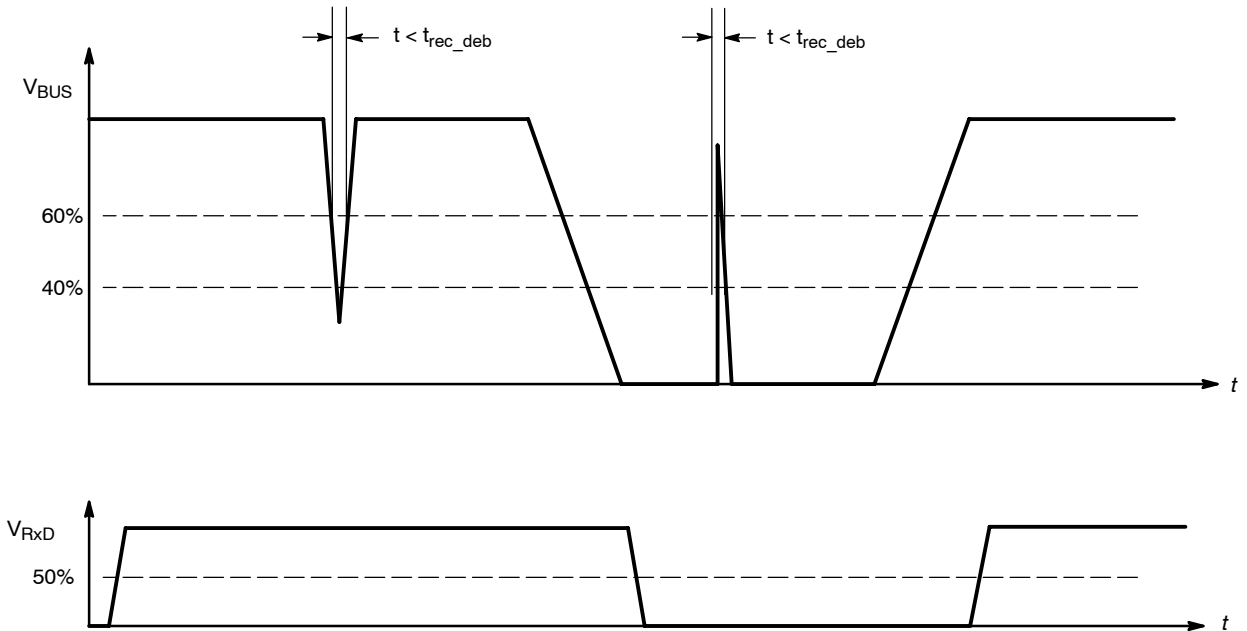


Figure 3. Receiver Debouncing Filter

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TEST CIRCUITS FOR DYNAMIC AND STATIC CHARACTERISTICS

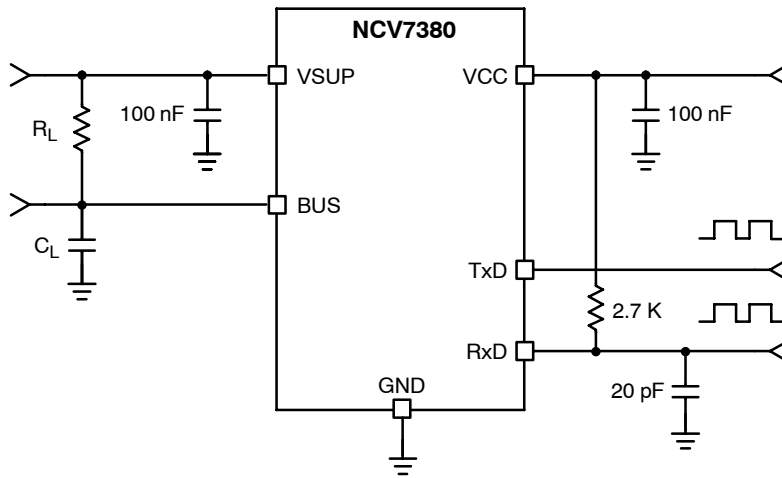


Figure 4. Test Circuit for Dynamic Characteristics

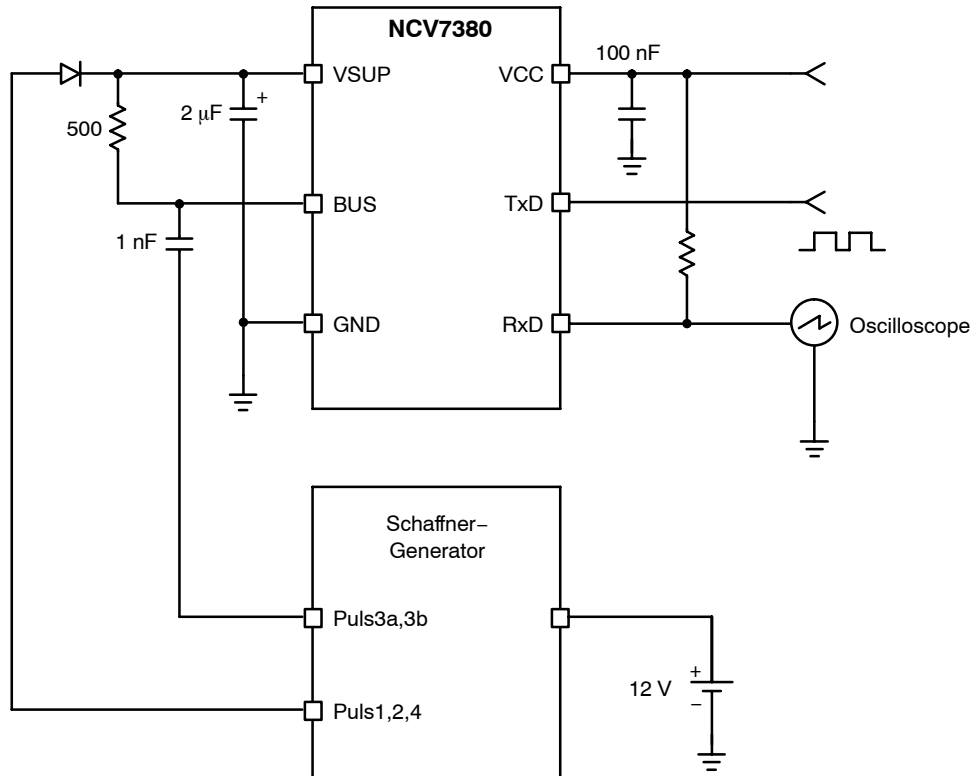


Figure 5. Test Circuit for Automotive Transients

Functional Description

Initialization

After *power on*, the chip automatically enters the recessive state (TxD = Open). Both V_{CC} and V_S must be present.

Operating Modes

All operation modes will be handled from the NCV7380 automatically.

Normal Mode

After power on, the IC switches automatically to normal mode. Bus communication is possible. If there is no communication on the bus line the power consumption of the IC is very low and does not require microprocessor control.

Thermal Shutdown Mode

If the junction temperature T_j is higher than $155^{\circ}C$, the NCV7380 could be switched into the thermal shutdown mode (bus driver will be switched off, receiver is on).

If T_j falls below the thermal shutdown temperature (typical $140^{\circ}C$) the NCV7380 will be switched to the normal mode.

LIN BUS Transceiver

The transceiver consists of a bus-driver (1.2 V @ 40 mA) with slew rate control and current limit, and a receiver with a high voltage comparator with filter circuitry.

BUS Input/Output

The recessive BUS level is generated from the integrated 30 k pullup resistor in series with a diode. The diode prevents reverse current on V_{BUS} when $V_{BUS} > V_S$.

No additional termination resistor is necessary to use the NCV7380 on LIN slave nodes. If this IC is used for LIN master nodes, it is necessary to terminate the bus with an external 1.0 k Ω resistor in series with a diode to V_{BAT} (Figure 9).

TxD Input

During transmission the signal on TxD will be transferred to the BUS driver for generating a BUS signal. To minimize the electromagnetic emission of the bus line, the BUS driver has integrated slew rate control and wave shaping.

Transmitting will be interrupted if thermal shutdown is active.

The CMOS compatible input TxD directly controls the BUS level:

TxD = low \rightarrow BUS = low (dominant level)

TxD = high \rightarrow BUS = high (recessive level)

The TxD pin has an internal pullup resistor connected to V_{CC} . This secures that an open TxD pin generates a recessive BUS level.

RxD Output

The signal on the BUS pin will be transferred continuously to the RxD pin. Short spikes on the bus signal are filtered with internal circuitry (Figure 3 and Figure 6).

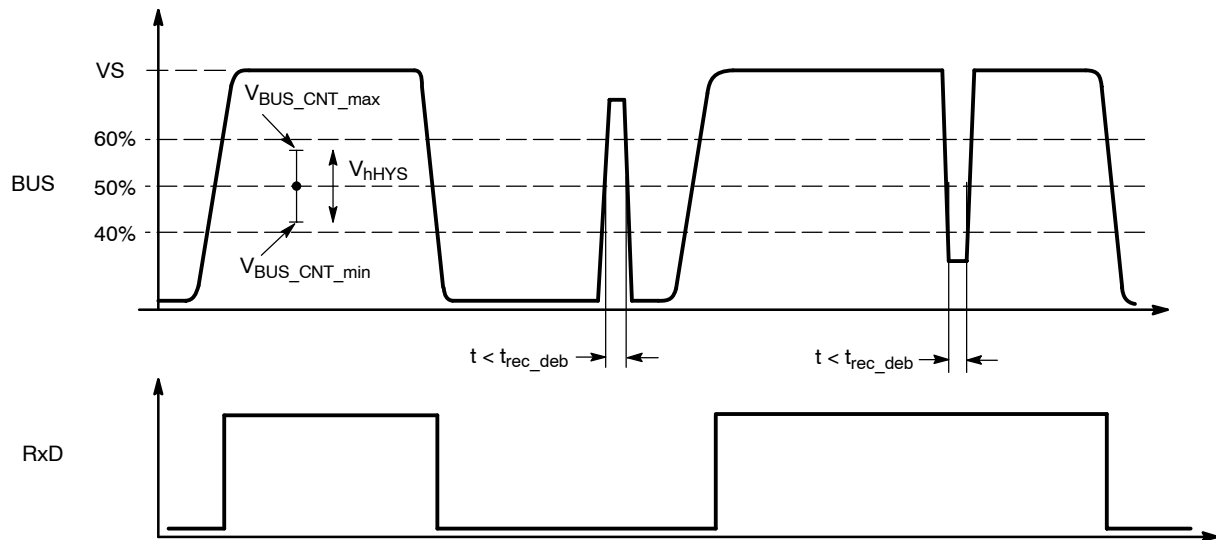


Figure 6. Receive Impulse Diagram

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The receive threshold values $V_{BUS_CNT_max}$ and $V_{BUS_CNT_min}$ are symmetrical to $0.5 \cdot V_S$ with a hysteresis of $0.16 \cdot V_S$ (typ). The LIN specific receive threshold is between $0.4 \cdot V_S$ and $0.6 \cdot V_S$.

The received BUS signal will be output to the RxD pin:

$$BUS < V_{BUS_CNT} - 0.5 \cdot V_{HYS} \\ \rightarrow RxD = \text{low (BUS dominant)}$$

$$BUS > V_{BUS_CNT} + 0.5 \cdot V_{HYS} \\ \rightarrow RxD = \text{high, floating (BUS recessive)}$$

RxD is a buffered open drain output with a typical load of:

Resistance: 2.7 k Ω

Capacitance: < 20 pF

Data Rate

The NCV7380 is a *constant slew rate* transceiver. The bus driver operates with a fixed slew rate range of 1.0 V/ μ s $\leq \Delta V/\Delta T \leq 3.0$ V/ μ s. This principle provides very good symmetry of the slope times between recessive to dominant and dominant to recessive slopes within the LIN bus load range (C_{BUS} , R_{term}).

The NCV7380 guarantees data rates up to 20 kBit within the complete bus load range under worst case conditions. The constant slew rate principle holds appropriate voltage levels and can operate within the LIN Protocol Specification for RC oscillator systems with a matching tolerance up to 2%.

Application Hints

LIN System Parameter

Bus Loading Requirements

| Parameter | Symbol | Min | Typ | Max | Unit |
|---|------------------|-----|------|------|------------|
| Operating Voltage Range | V_{BAT} | 8.0 | – | 18 | V |
| Voltage Drop of Reverse Protection Diode | V_{Drop_rev} | 0.4 | – | 1.0 | V |
| Voltage Drop of Bus Decouple Diode in the Master Node | V_{Drop_dec} | 0.4 | – | 1.0 | V |
| Battery Offset Voltage | V_{batoff} | – | – | 0.1 | V_{BAT} |
| Ground Offset Voltage | V_{goff} | – | – | 0.1 | V_{BAT} |
| Master Termination Resistor | R_{pu_master} | 900 | 1000 | 1100 | Ω |
| Slave Termination Resistor | R_{pu_slave} | 20 | 30 | 60 | k Ω |
| Number of System Nodes | N | 2 | – | 16 | – |
| Network Distance between any two ECU Nodes | B_{US_length} | – | – | 40 | m |
| Line Capacitance | C_{LINE} | – | 100 | 150 | pF/m |
| Capacitance of Master Node | C_{Master} | – | 220 | – | pF |
| Capacitance of Slave Node | C_{Slave} | 195 | 220 | 300 | pF |
| Network Total Capacitance | C_{t1} | 1.0 | 4.0 | 10 | nF |
| Network Total Resistance | R_{t1} | 537 | – | 863 | Ω |
| Time Constant of Overall System | τ_{net} | 1.0 | – | 5.0 | μ s |

Operating Under Disturbance

Loss of Battery

If V_S and V_{CC} are disconnected from the battery, the bus pin is in high impedance state. There is no impact to the bus traffic.

Loss of Ground

In case of an interrupted ground connection from V_S and V_{CC} , there is no influence to the bus line.

Short Circuit BUS to Battery

The transmitter output current is limited to 200 mA (max) in case of short circuit to battery.

Short Circuit BUS to Ground

Negative voltages on the bus pin are limited to current through the internal 30 k resistor and series diode from V_S .

Thermal Overload

The NCV7380 is protected against thermal overloads. If the chip temperature exceeds the thermal shutdown threshold, the transmitter is switched off until thermal recovery. The receiver continues to work during thermal shutdown.

Undervoltage V_{CC}

The V_{CC} undervoltage lockout feature disables the transmitter until it is above the undervoltage lockout threshold to prevent undesirable bus traffic.

Recommendations for System Design

The goal of the LIN physical layer standard is to have a universal definition of the LIN system for plug and play solutions in LIN networks up to 20 kBd bus speeds.

In case of small and medium LIN networks, it's recommended to adjust the total network capacitance to at least 4.0 nF for good EMC and EMI behavior. This can be done by setting only the master node capacitance. The slave node capacitance should have a unit load of typically 220 pF for good EMC/EMI behavior.

In large networks with long bus lines and the maximum number of nodes, some system parameters can exceed the defined limits and the LIN system designer must intervene.

The whole capacitance of a slave node is not only the unit load capacitor itself. Additionally, there is the capacitance of wires and connectors, and the internal capacitance of the LIN transmitter. This internal capacitance is strongly dependent on the technology of the IC manufacturer and should be in the range of 30 pF to 150 pF. If the bus lines have a total length of nearly 40m, the total bus capacitance can exceed the LIN system limit of 10 nF.

A second parameter of concern is the integrated slave termination resistor tolerance. If most of the slave nodes have a slave termination resistance at the allowed maximum of 60 kΩ, the total network resistance is more than 700 Ω. Even if the total network capacitance is below or equal to the maximum specified value of 10 nF, the network time constant is higher than 7.0 μs.

This problem can be solved only by adjusting the master termination resistor to the required maximum network time constant of 5.0 μs (max).

NOTE: *The NCV7380 meets the requirements for implementation in RC-based slave nodes. The LIN Protocol Specification requires the deviation of the slave node clock to the master node clock after synchronization must not differ by more than ±2%.*

Setting the network time constant is necessary in large networks (primarily resistance) and also in small networks (primarily capacitance).

MIN/MAX SLOPE TIME CALCULATION

(In accordance to the LIN System Parameter Table)

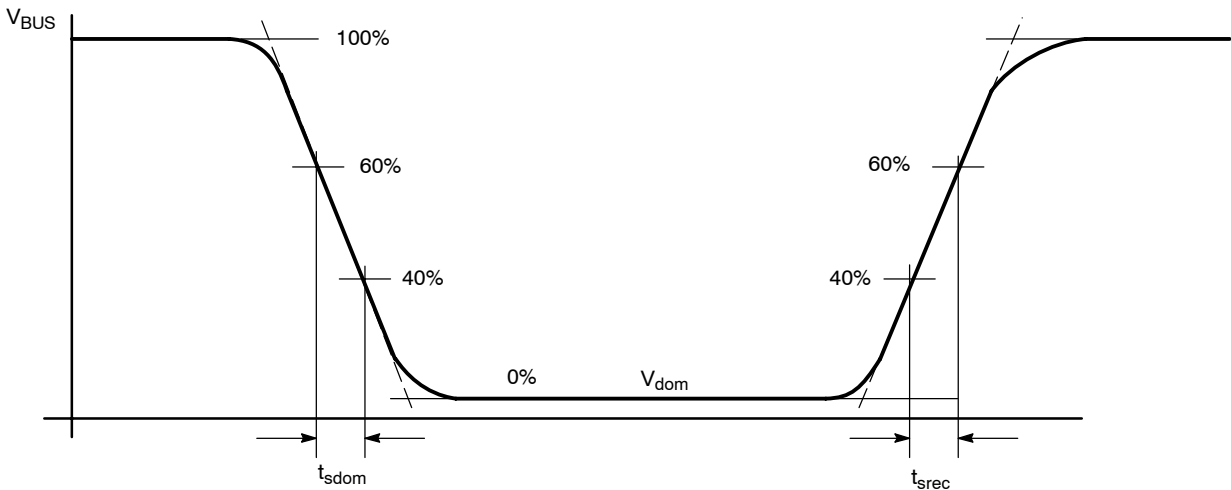


Figure 7. Slope Time and Slew Rate Calculation

(In accordance to LIN physical layer specification 1.3)

The slew rate of the bus voltage is measured between 40% and 60% of the output voltage swing (linear region). The output voltage swing is the difference between dominant and recessive bus voltage.

$$dV/dt = 0.2 * V_{swing} / (t_{40\%} - t_{60\%})$$

The slope time is the extension of the slew rate tangent until the upper and lower voltage swing limits:

$$t_{slope} = 5 * (t_{40\%} - t_{60\%})$$

The slope time of the recessive to dominant edge is directly determined by the slew rate control of the transmitter:

$$t_{slope} = V_{swing} / dV/dt$$

The dominant to recessive edge is influenced from the network time constant and the slew rate control, because it's a passive edge. In case of low battery voltages and high bus loads the rising edge is only determined by the network. If the rising edge slew rate exceeds the value of the dominant one, the slew rate control determines the rising edge.

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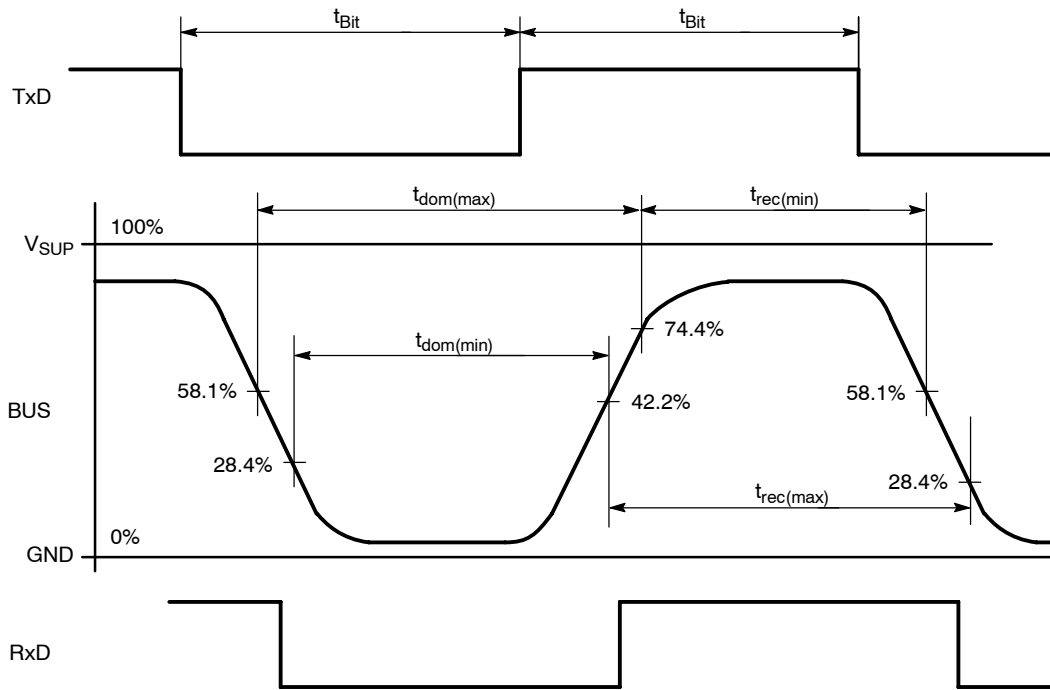


Figure 8. Duty Cycle Measurement and Calculation in Accordance to LIN Physical Layer Specification 2.0

Duty Cycle Calculation

With the timing parameters shown in Figure 8 two duty cycles, based on $t_{rec(min)}$ and $t_{rec(max)}$ can be calculated as follows:

$$D1^* = t_{rec(min)} / (2 \times t_{Bit})$$

$$D2^* = t_{rec(max)} / (2 \times t_{Bit})$$

For proper operation at 20 KBit/s (bit time is 50 μ s) the LIN driver has to fulfill the duty cycles specified in the AC characteristics for supply voltages of 7...18 V and the three defined standard loads.

Due to this simple definition there is no need to measure slew rates, slope times, transmitter delays and dominant

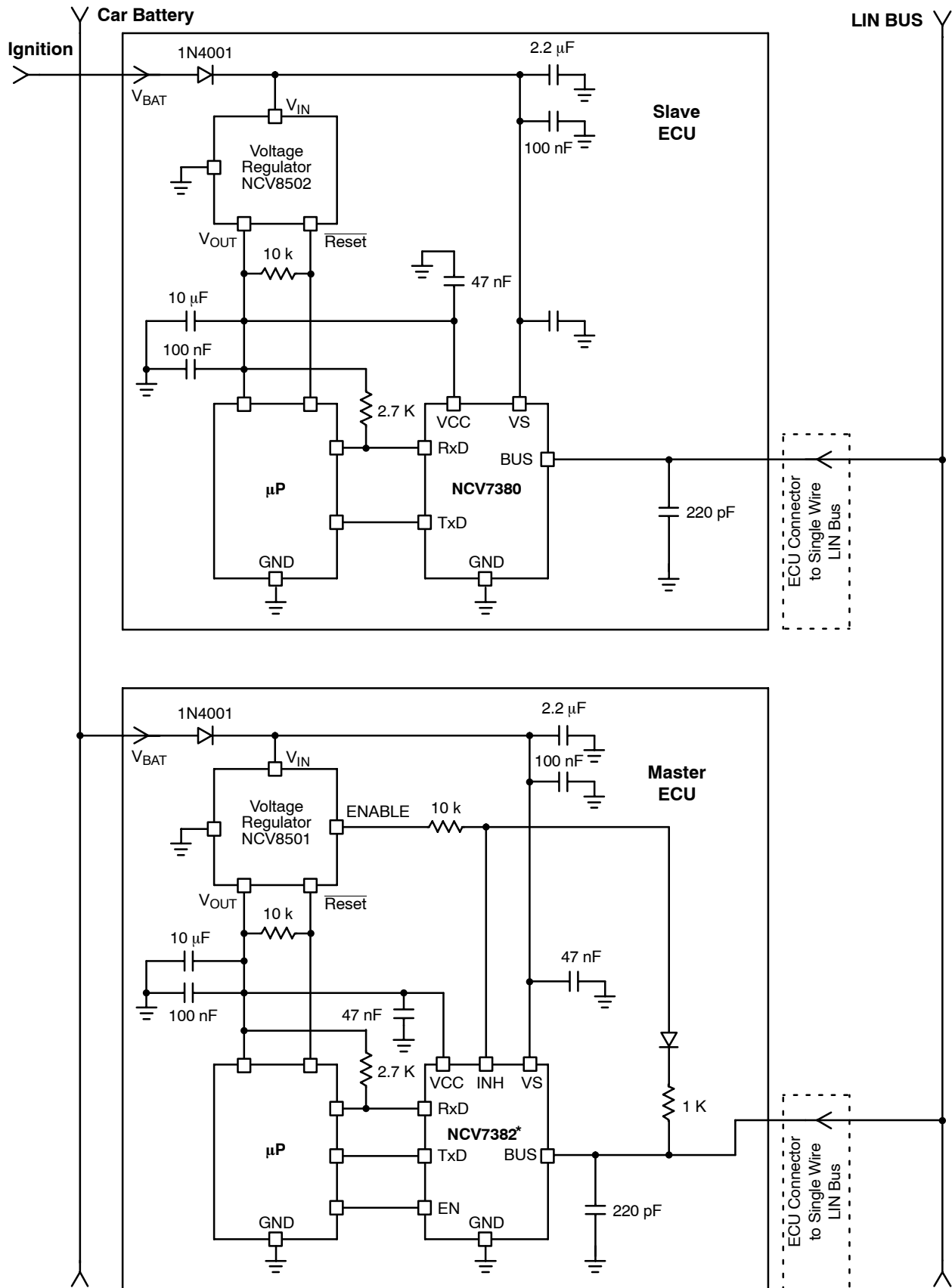
voltage levels as specified in the LIN physical layer specification 1.3.

The devices within the D1/D2 duty cycle range also operates in applications with reduced bus speed of 10.4 kBit/s or below.

In order to minimize EME, the slew rates of the transmitter can be reduced (by up to ≈ 2 times). Such devices have to fulfill the duty cycle definition D3/D4 in the LIN physical layer specification 2.0. Devices within this duty cycle range *cannot* operate in higher frequency 20 kBit/s applications.

*D1 and D2 are defined in the LIN protocol specification 2.0.

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*The NCV7382 is a pin compatible transceiver with INH control.

Figure 9. Application Circuitry

NCV7380

ESD/EMC Remarks

General Remarks

Electronic semiconductor products are sensitive to Electro Static Discharge (ESD). Always observe ESD control procedures whenever handling semiconductor products.

ESD Test

The NCV7380 is tested according to MIL883D (Human Body Model).

EMC

The test on EMC impacts is done according to ISO 7637-1 for power supply pins and ISO 7637-3 for data and signal pins.

POWER SUPPLY PIN VS

| Test Pulse | Condition | Duration |
|------------|---|-----------------------|
| 1 | $t_1 = 5.0 \text{ s}/U_S = -100 \text{ V}/t_D = 2.0 \text{ ms}$ | 5000 Pulses |
| 2 | $t_1 = 0.5 \text{ s}/U_S = 100 \text{ V}/t_D = 0.05 \text{ ms}$ | 5000 Pulses |
| 3a/b | $U_S = -150 \text{ V}/U_S = 100 \text{ V}$ Burst 100 ns/10 ms/90 ms Break | 1 h |
| 5 | $R_i = 0.5 \Omega, t_D = 400 \text{ ms}$ $t_r = 0.1 \text{ ms}/U_P + U_S = 40 \text{ V}$ | 10 Pulses Every 1 Min |

DATA AND SIGNAL PINS BUS

| Test Pulse | Condition | Duration |
|------------|--|-------------|
| 1 | $t_1 = 5.0 \text{ s}/U_S = -100 \text{ V}/t_D = 2.0 \text{ ms}$ | 1000 Pulses |
| 2 | $t_1 = 0.5 \text{ s}/U_S = 100 \text{ V}/t_D = 0.05 \text{ ms}$ | 1000 Pulses |
| 3a/b | $U_S = -150 \text{ V}/U_S = 100 \text{ V}$ Burst 100 ns/10 ms/90 ms Break | 1000 Burst |

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

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- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.80 | 5.00 | 0.189 | 0.197 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.053 | 0.069 |
| D | 0.33 | 0.51 | 0.013 | 0.020 |
| G | 1.27 BSC | | 0.050 BSC | |
| H | 0.10 | 0.25 | 0.004 | 0.010 |
| J | 0.19 | 0.25 | 0.007 | 0.010 |
| K | 0.40 | 1.27 | 0.016 | 0.050 |
| M | 0° | 8° | 0° | 8° |
| N | 0.25 | 0.50 | 0.010 | 0.020 |
| S | 5.80 | 6.20 | 0.228 | 0.244 |

GENERIC MARKING DIAGRAM*

SOLDERING FOOTPRINT*



XXXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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- | | | | |
|--|---|---|---|
| <p>STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER</p> | <p>STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1</p> | <p>STYLE 3: PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1</p> | <p>STYLE 4: PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE</p> |
| <p>STYLE 5: PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE</p> | <p>STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE</p> | <p>STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd</p> | <p>STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 8. COLLECTOR, #1</p> |
| <p>STYLE 9: PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON</p> | <p>STYLE 10: PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND</p> | <p>STYLE 11: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1</p> | <p>STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN</p> |
| <p>STYLE 13: PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN</p> | <p>STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN</p> | <p>STYLE 15: PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON</p> | <p>STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1</p> |
| <p>STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC</p> | <p>STYLE 18: PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE</p> | <p>STYLE 19: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1</p> | <p>STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN</p> |
| <p>STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6</p> | <p>STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND</p> | <p>STYLE 23: PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT</p> | <p>STYLE 24: PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE</p> |
| <p>STYLE 25: PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT</p> | <p>STYLE 26: PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC</p> | <p>STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN</p> | <p>STYLE 28: PIN 1. SW_TO_GND 2. DASIC OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN</p> |
| <p>STYLE 29: PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1</p> | <p>STYLE 30: PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1</p> | | |

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